

RJJ0601JPE-VB Datasheet

P-Channel 60-V (D-S) 175 °C MOSFET

PRODUCT S	PRODUCT SUMMARY				
V _{DS} (V) R _{DS(on)} (Ω)		I _D (A) ^d			
- 60	0.0065 at V _{GS} = - 10 V	- 110			
- 00	0.0085 at V _{GS} = - 4.5 V	- 110			

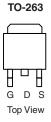
FEATURES

- TrenchFET[®] Power MOSFET
- Package with Low Thermal Resistance

GO

• 100 % R_g Tested









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ABSOLUTE MAXIMUM RATINGS $T_C = 2$	5 °C, unless other	wise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	V	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current ^d	T _C = 25 °C	l _D	- 110	A	
(T _J = 175 °C)	T _C = 125 °C		- 75		
Pulsed Drain Current		I _{DM}	I _{DM} - 200		
Avalanche Current	L = 0.1 mH	I _{AS}	- 85	1	
Single Pulse Avalanche Energy ^d		E _{AS}	211	mJ	
	T _C = 25 °C	Р	272 ^c	w	
Maximum Power Dissipation	$T_{C} = 25 \text{ °C}$ $T_{A} = 25 \text{ °C}^{b}$	P _D	3.75 ^b		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount ^d	R _{thJA}	40	°C/W	
Junction-to-Case		R _{thJC}	0.55	0/10	

Notes:

a. Duty cycle \leq 1 %.

b. When Mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.

d. Limited by Package.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

SPECIFICATIONS T _J = 25 $^{\circ}$	C, unless o	therwise noted				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = - 250 μ A	- 60			V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 1		- 3	
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	μA
	I _{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50	
		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 175 °C			- 250	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 V, V_{GS} = -10 V$	- 120			А
		V _{GS} = - 10 V, I _D = - 30 A		0.0065		- Ω
Drain-Source On-State Resistance ^a	P	V_{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C		0.0129		
	R _{DS(on)}	V_{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C		0.016		
		V _{GS} = - 4.5 V, I _D = - 20 A		0.0085		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 50 A	20			S
Dynamic ^b	•	· · · · · · · · · · · · · · · · · · ·		•		
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz		9200		pF
Output Capacitance	C _{oss}			975		
Reverse Transfer Capacitance	C _{rss}			760		
Total Gate Charge ^c	Qg			160	240	nC
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 30 V, V _{GS} = - 10 V, I _D = - 110 A		40		
Gate-Drain Charge ^c	Q _{gd}			36		
Gate Resistance	R _q	f = 1 MHz	1.5	3	4.5	Ω
Turn-On Delay Time ^c	t _{d(on)}			20	30	
Rise Time ^c	t _r	$V_{DD} = -30 \text{ V}, \text{ R}_{1} = 0.27 \Omega$		190	285	ns
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -110 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 2.5 \Omega$		140	210	
Fall Time ^c	t _f	-		300	450	
Source-Drain Diode Ratings and Ch	aracteristics	T _C = 25 °C ^b				
Continuous Current	Is				- 110	A
Pulsed Current	I _{SM}				- 200	
Forward Voltage ^a	V _{SD}	I _F = - 50 A, V _{GS} = 0 V		- 1.0	- 1.5	V
Reverse Recovery Time	t _{rr}			60	90	ns
Peak Reverse Recovery Charge	I _{RM(REC)}	I _F = - 50 A, di/dt = 100 A/μs		- 3	- 4.5	А
Reverse Recovery Charge	Q _{rr}	1		0.09	0.2	μC

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

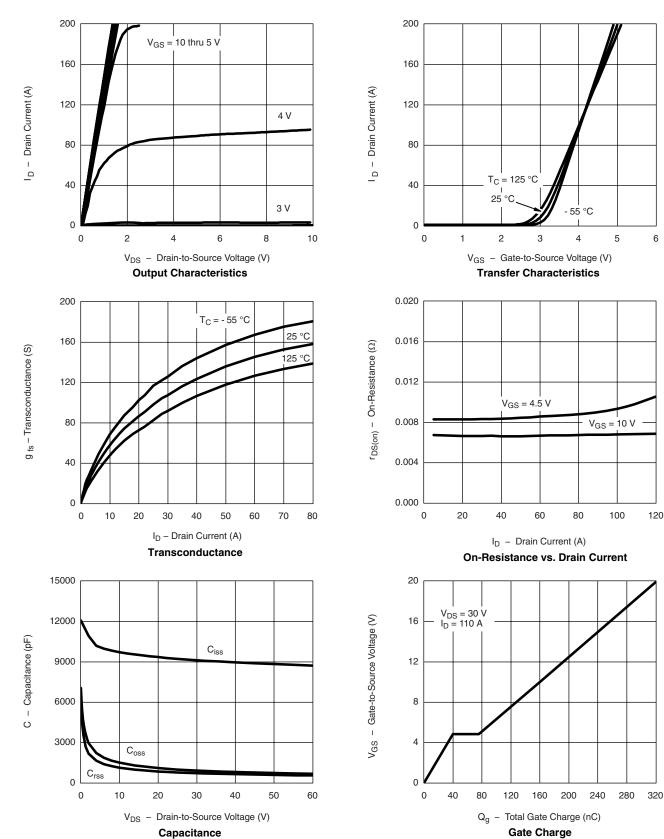
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



T_J = 25 °C

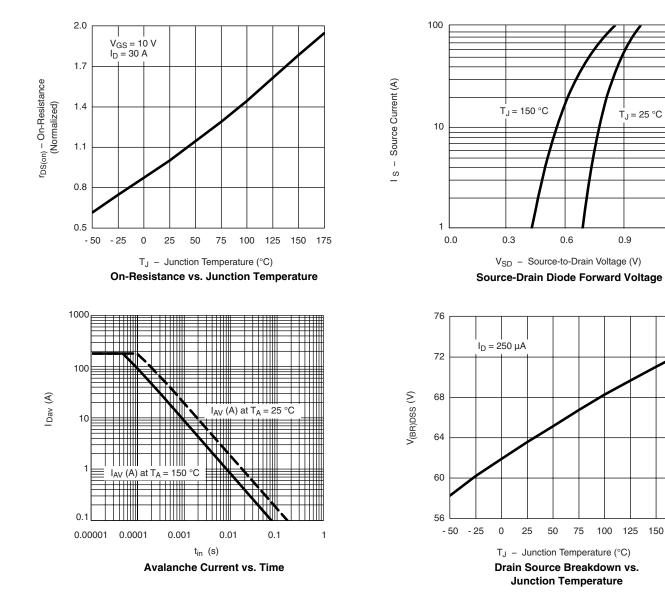
0.9

100

125 150 175

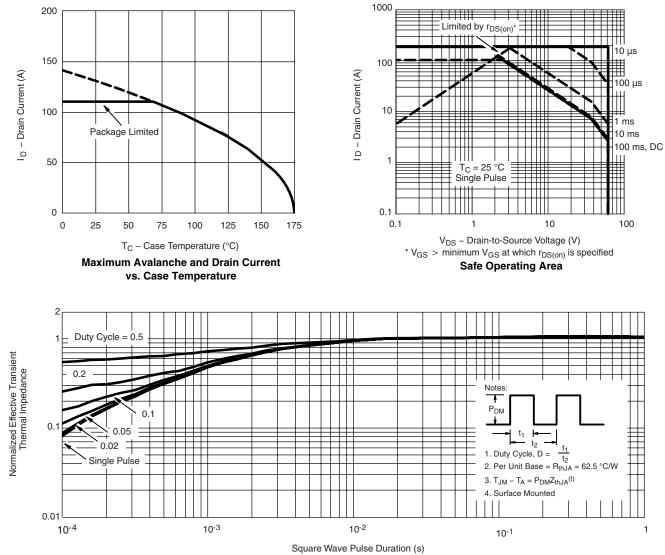
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





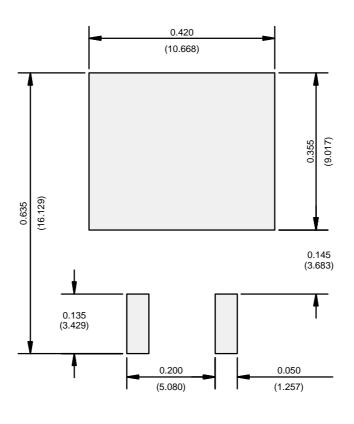
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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